

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An aqueous dispersion having a pH value of between 3 and 7 ~~containing~~ comprising 1 to 35 wt.% of a pyrogenically produced silicon-aluminium mixed oxide powder with a specific surface area of 5 to 400 m<sup>2</sup>/g, ~~characterised in that~~ wherein

- the proportion of aluminium oxide in the powder is between 90 and 99.9 wt.% or between 0.01 and 10 wt.%;
- the surface of the powder comprises zones of aluminium oxide and silicon dioxide; and
- the powder exhibits no signals for crystalline silicon dioxide in an X-ray diffractogram.

Claim 2 (Currently Amended): ~~An~~ The aqueous dispersion according to claim 1, ~~characterised in that~~ wherein the dispersion comprises 0.3-20 wt.% of an ~~oxidising~~ oxidizing agent.

Claim 3 (Currently Amended): ~~An~~ The aqueous dispersion according to claim 1 ~~or 2~~, ~~characterised in that it contains~~ wherein the dispersion comprises additives.

Claim 4 (Currently Amended): ~~An~~ The aqueous dispersion according to ~~claims 1 to 3~~ claim 1, ~~characterised in that~~ wherein, in addition to the silicon-aluminium mixed oxide powder, ~~it contains~~ the dispersion comprises at least a further metal oxide powder selected from the group ~~comprising~~ consisting of silicon dioxide, aluminium oxide, cerium oxide, zirconium oxide and titanium dioxide.

Claim 5 (Currently Amended): ~~Use of the aqueous dispersion according to claims 1 to 4 for the~~ A method of chemical-mechanical polishing of conductive, metallic films comprising polishing conductive, metallic films with the aqueous dispersion according to claim 1.

Claim 6 (Currently Amended): ~~Use of the aqueous dispersion according to claims 1 to 4 for the~~ A method of chemical-mechanical polishing of conductive, metallic films ~~which~~ comprising polishing conductive, metallic films with the aqueous dispersion according to claim 1, wherein the conductive, metallic films are applied on an insulating barrier layer.